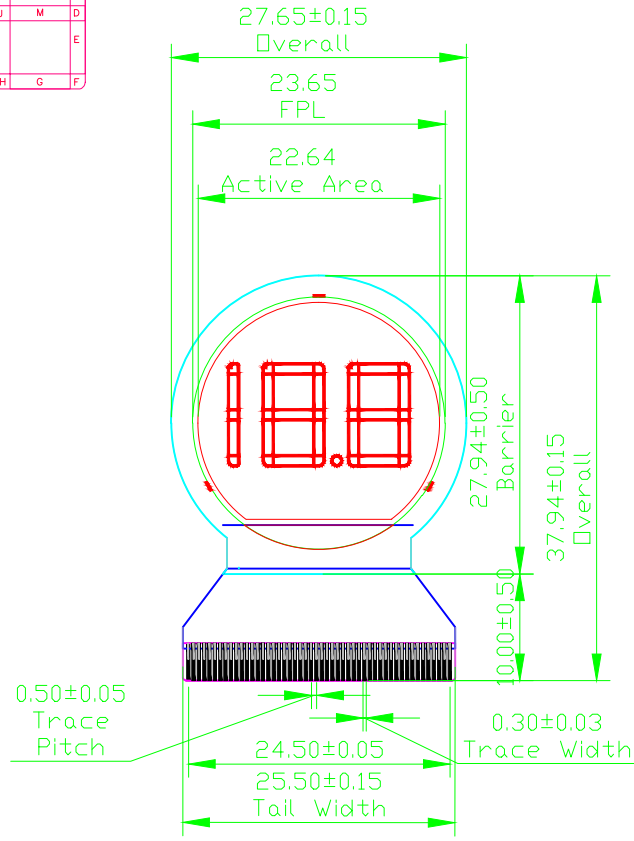
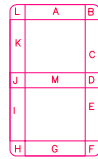


33seg round PIN_MAP		
PIN MAP		
PIN	Description	segment
1	Top electrode	
2	Field	1
3	A	A 2
4	A	B 3
5	A	C 4
6	A	D 5
7	A	E 6
8	A	F 7
9	A	G 8
10	A	H 9
11	A	I 10
12	DP	11
13	A	J 12
14	B	F 13
15	A	K 14
16	A	L 15
17	A	M 16
18	B	E 17
19	B	D 18
20	B	C 19
21	B	G 20
22	B	H 21
23	B	B 22
24	B	I 23
25	B	J 24
26	B	K 25
27	B	L 26
28	C	H 27
29	C	I 28
30	C	J 29
31	C	K 30
32	C	L 31
33	B	A 32
34	B	M 33



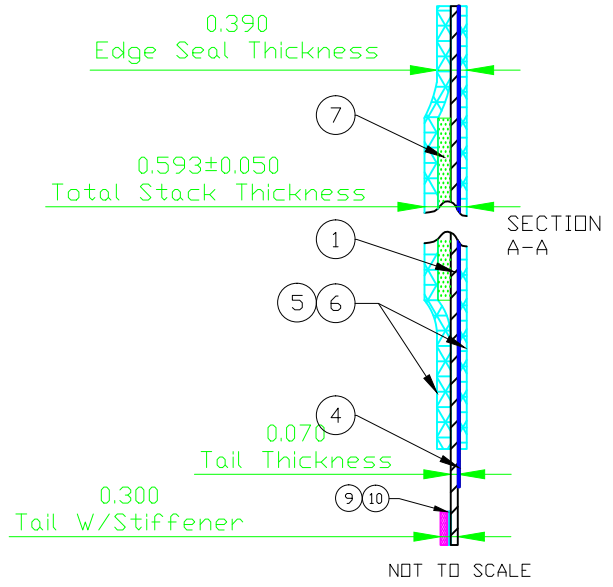
25-50  
blank  
  
Connector-  
Tyco  
5-1734592-0

REV.	DESCRIPTION	DESIGN	DATE
	INITIAL RELEASE		

SDC 2 (100UM THICK PTF BACKPLANE) MATERIALS LIST				
ITEM	LAYER COLOR	DESCRIPTION	MATERIAL	THICKNESS (µm)
1		BACKPLANE	MYLAR PET	100
2		ELECTRODE-FRONT	CARBON	12.50
3		ELECTRODE-REAR 1	SILVER	12.50
4		ELECTRODE-REAR 2	CARBON	12.50
5		DIELECTRIC	DIELECTRIC	35
6		FRONT BARRIER	EINK 110-1031	175
7		REAR BARRIER	EINK 110-1032	100
8		FPL	340-1934 (220S)	175
9		STIFFENER	MYLAR PET	180
10		STIFFENER ADHESIVE	PSA	50

Note:  
1. SDC should be built in accordance with the MFG Spec.  
2. Critical Dimensions Should Be Denoted with Min-Max Tolerances.



MATERIAL	HEAT & SURFACE TREATMENT	E Ink Holdings Inc.		
APPROVE	S ONEIL	SCALE	LIMIT	PROJECTION METHOD
CHECK	S ONEIL	1/1	MR	
DESIGN	S ONEIL	ORIGINAL NAME	DWG. NO.	REV. SHEET
			2.5 Digit Numeric Round	SS009221 03 1/1